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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

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PF08127B

MOS FET Power Amplifier Module
for E-GSM and DCS1800/1900 Triple Band Handy Phone



ADE-208-1606 (Z)

Rev.0
Oct. 2002

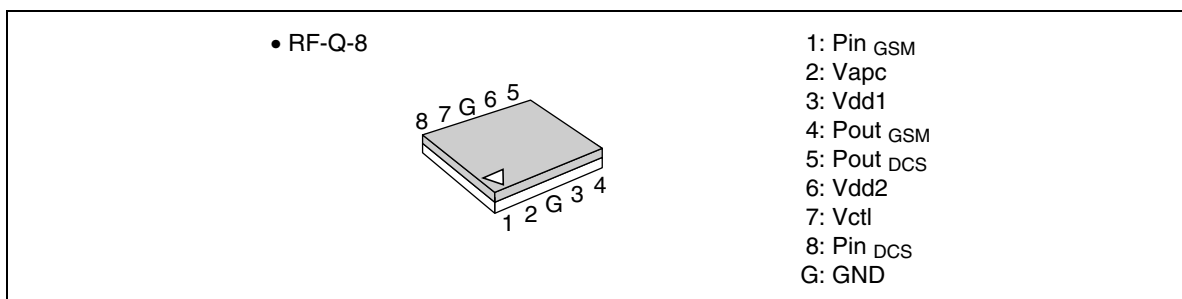
Application

- Triple band amplifier for
E-GSM (880 MHz to 915 MHz), DCS1800/1900 (1710 MHz to 1785 MHz, 1850 MHz to 1910 MHz).
- For 3.5 V & GPRS Class12 operation compatible

Features

- All in one including output matching circuit
- Simple external circuit
- Simple power control
- High gain 3stage amplifier : 0 dBm input Typ
- Lead less thin & Small package : 8.0×10.0 mm Typ \times 1.5 mm Max
- High efficiency : 55% Typ at 35.0 dBm for E-GSM
47% Typ at 32.5 dBm for DCS1800
47% Typ at 32.0 dBm for DCS1900

Pin Arrangement



PF08127B

Absolute Maximum Ratings *¹

(T_c = 25°C)

Item	Symbol	Rating	Unit	Remark
Supply voltage	V _{dd}	7.0	V	at no-operation
		5.0	V	at operation (50 Ω load)
Supply current	I _{dd} _{GSM}	3.5	A	
	I _{dd} _{DCS}	2	A	
V _{ctl} voltage	V _{ctl}	4	V	
V _{apc} voltage	V _{apc}	4	V	
Input power	P _{in}	10	dBm	
Operating case temperature * ²	T _c (op)	−30 to +100	°C	
Storage temperature	T _{stg}	−40 to +100	°C	
Output power	P _{out} _{GSM}	5	W	
	P _{out} _{DCS}	3	W	

- Notes: 1. The maximum ratings shall be valid over both the E-GSM-band (880 to 915 MHz), and the DCS1800/1900-band (1710 to 1785 MHz, 1850 to 1910 MHz).
2. These are specified at pulsed operation with pulse width = 1154 μsec and duty cycle of 2:8.

Electrical Characteristics for DC

(T_c = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Drain cutoff current	I _{ds}	—	—	20	μA	V _{dd} = 4.7 V, V _{apc} = 0 V, V _{ctl} = 0.2 V
V _{apc} control current	I _{apc}	—	—	2.0	mA	V _{apc} = 2.2 V
V _{ctl} control current	I _{ctl}	—	—	2	μA	V _{ctl} = 3 V

Electrical Characteristics for E-GSM band

(T_c = 25°C)

Test conditions unless otherwise noted:

f = 880 to 915 MHz, V_{dd1} = V_{dd2} = 3.5 V, Pin = 0 dBm, V_{ctl} = 2.0 V, R_g = R_l = 50 Ω, T_c = 25°C,

Pulse operation with pulse width 1154 μs and duty cycle 2:8 shall be used.

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Frequency range	f	880	—	915	MHz	
Band select (GSM active)	V _{ctl}	2.0	—	2.8	V	
Input power	Pin	−2	0	2	dBm	
Control voltage range	V _{apc}	0.2	—	2.2	V	
Supply voltage	V _{dd}	3.1	3.5	4.5	V	
Total efficiency	η _T	47	55	—	%	P _{out GSM} = 35 dBm, V _{apc} = controlled
2nd harmonic distortion	2nd H.D.	—	−15(−50)	0(−35)	dBm(dBc)	
3rd harmonic distortion	3rd H.D.	—	−10(−45)	0(−35)	dBm(dBc)	
4th~8th harmonic distortion	4th~8th H.D.	—	—	0(−35)	dBm(dBc)	
Input VSWR	VSWR (in)	—	1.5	3	—	
Output power (1)	P _{out} (1)	35.0	36.0	—	dBm	V _{apc} = 2.2 V
Output power (2)	P _{out} (2)	33.5	34.5	—	dBm	V _{dd} = 3.1 V, V _{apc} = 2.2 V, T _c = +85°C
I _{dd} at Low power	—	—	—	300	mA	P _{out GSM} = 7 dBm
Isolation	—	—	−48	−37	dBm	V _{apc} = 0.2 V
Isolation at DCS RF-output when GSM is active	—	—	−25	−18	dBm	P _{out GSM} = 35 dBm, Measured at f = 1760 to 1830 MHz
Switching time	t _r , t _f	—	1	2	μs	P _{out GSM} = 5 to 35 dBm
Stability	—	No parasitic oscillation > −36 dBm			—	V _{dd} = 3.1 to 4.5 V, P _{out} ≤ 35 dBm, V _{apc GSM} ≤ 2.2 V, R _g = 50 Ω, Output VSWR = 6 : 1 All phase angles
Load VSWR tolerance	—	No degradation or Permanent degradation			—	V _{dd} = 3.1 to 4.5 V, P _{out GSM} ≤ 35 dBm, V _{apc GSM} ≤ 2.2 V, R _g = 50 Ω, t ≤ 20 sec., Output VSWR = 10 : 1 All phase angles
Load VSWR tolerance at GPRS CLASS 12 operation	—	No degradation or Permanent degradation			—	V _{dd} = 3.1 to 4.2 V, P _{out GSM} ≤ 35 dBm, V _{apc GSM} ≤ 2.2 V, R _g = 50 Ω, t ≤ 20 sec., T _c ≤ 90°C, Output VSWR = 10 : 1 All phase angles
Slope P _{out} /V _{apc}	—	—	160	200	dB/V	P _{out GSM} = 5 to 35 dBm
AM output	—	—	15	20	%	P _{out GSM} = 5 to 35 dBm, 4% AM modulation at input 50 kHz modulation frequency

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Electrical Characteristics for DCS1800 band

(T_c = 25°C)

Test conditions unless otherwise noted:

f = 1710 to 1785 MHz, V_{dd1} = V_{dd2} = 3.5 V, Pin = 0 dBm, V_{ctl} = 0 V, R_g = R_l = 50 Ω, T_c = 25°C,

Pulse operation with pulse width 1154 μs and duty cycle 2:8 shall be used.

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Frequency range	f	1710	—	1785	MHz	
Band select (DCS active)	V _{ctl}	0	—	0.1	V	
Input power	Pin	-2	0	2	dBm	
Control voltage range	V _{apc}	0.2	—	2.2	V	
Supply voltage	V _{dd}	3.1	3.5	4.5	V	
Total efficiency	η _r	40	47	—	%	P _{out} _{DCS} = 32.5 dBm, V _{apc} = controlled
2nd harmonic distortion	2nd H.D.	—	-14.5(-47)	-2.5(-35)	dBm(dBc)	
3rd harmonic distortion	3rd H.D.	—	-7.5(-40)	-2.5(-35)	dBm(dBc)	
4th~8th harmonic distortion	4th~8th H.D.	—	—	-2.5(-35)	dBm(dBc)	
Input VSWR	VSWR (in)	—	1.5	3	—	
Output power (1)	P _{out} (1)	32.5	33.5	—	dBm	V _{apc} = 2.2 V
Output power (2)	P _{out} (2)	31.0	32.0	—	dBm	V _{dd} = 3.1 V, V _{apc} = 2.2 V, T _c = +85°C,
I _{dd} at Low power	—	—	—	150	mA	P _{out} _{DCS} = 5 dBm
Isolation	—	—	-42	-37	dBm	V _{apc} = 0.2 V
Switching time	t _r , t _f	—	1	2	μs	P _{out} _{DCS} = 0 to 32.5 dBm
Stability	—	No parasitic oscillation > -36 dBm			—	V _{dd} = 3.1 to 4.5 V, P _{out} _{DCS} ≤ 32.5 dBm, V _{apc} ≤ 2.2 V, R _g = 50 Ω, Output VSWR = 6 : 1 All phase angles
Load VSWR tolerance	—	No degradation or Permanent degradation			—	V _{dd} = 3.1 to 4.5 V, P _{out} _{DCS} ≤ 32.5 dBm, V _{apc} ≤ 2.2 V, R _g = 50 Ω, t ≤ 20 sec., Output VSWR = 10 : 1 All phase angles
Load VSWR tolerance at GPRS CLASS 12 operation	—	No degradation or Permanent degradation			—	V _{dd} = 3.1 to 4.2 V, P _{out} _{DCS} ≤ 32.5 dBm, V _{apc} ≤ 2.2 V, R _g = 50 Ω, t ≤ 20 sec., T _c ≤ 90°C, Output VSWR = 10 : 1 All phase angles
Slope P _{out} /V _{apc}	—	—	160	200	dB/V	P _{out} _{DCS} = 0 to 32.5 dBm
AM output	—	—	15	20	%	P _{out} _{DCS} = 0 to 32.5 dBm, 4% AM modulation at input 50 kHz modulation frequency

Electrical Characteristics for DCS1900 band

(Tc = 25°C)

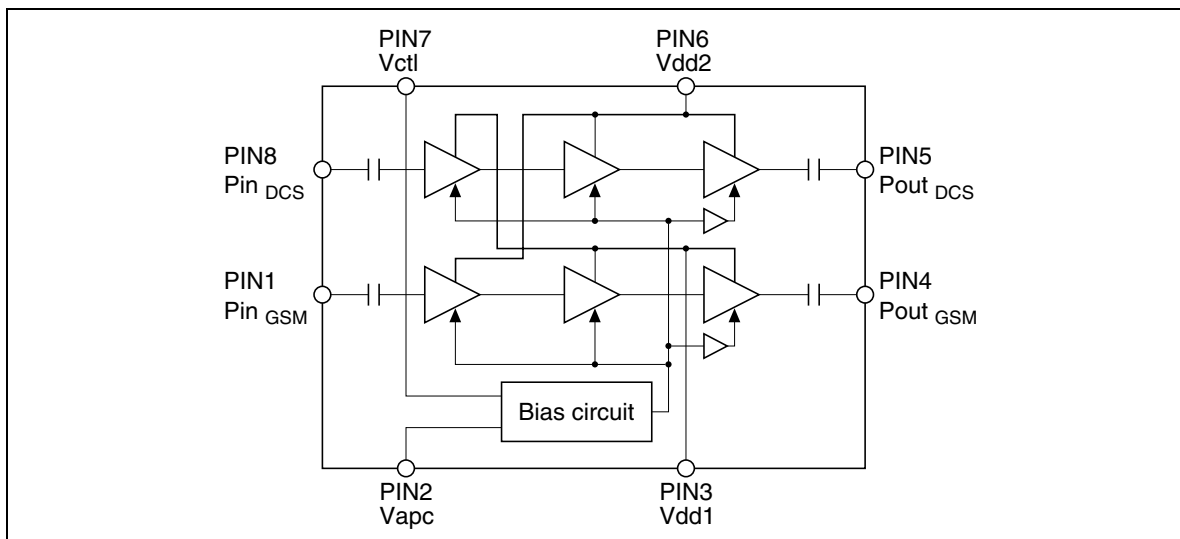
Test conditions unless otherwise noted:

f = 1850 to 1910 MHz, Vdd1 = Vdd2 = 3.5 V, Pin = 0 dBm, Vctl = 0.2 V, Rg = Rl = 50 Ω, Tc = 25°C,
Pulse operation with pulse width 1154 μs and duty cycle 2:8 shall be used.

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Frequency range	f	1850	—	1910	MHz	
Band select (DCS active)	Vctl	0	—	0.1	V	
Input power	Pin	-2	0	2	dBm	
Control voltage range	Vapc	0.2	—	2.2	V	
Supply voltage	Vdd	3.1	3.5	4.5	V	
Total efficiency	η_T	40	47	—	%	Pout _{DCS} = 32.0 dBm, Vapc = controlled
2nd harmonic distortion	2nd H.D.	—	-15(-47)	-3(-35)	dBm(dBc)	
3rd harmonic distortion	3rd H.D.	—	-8(-40)	-3(-35)	dBm(dBc)	
4th~8th harmonic distortion	4th~8th H.D.	—	—	-3(-35)	dBm(dBc)	
Input VSWR	VSWR (in)	—	1.5	3	—	
Output power (1)	Pout (1)	32.0	33.0	—	dBm	Vapc = 2.2 V
Output power (2)	Pout (2)	30.5	31.5	—	dBm	Vdd = 3.1 V, Vapc = 2.2 V, Tc = +85°C
Idd at Low power	—	—	—	150	mA	Pout _{DCS} = 5 dBm
Isolation	—	—	-42	-37	dBm	Vapc = 0.2 V
Switching time	t _r , t _f	—	1	2	μs	Pout _{DCS} = 0 to 32.0 dBm
Stability	—	No parasitic oscillation > -36 dBm			—	Vdd = 3.1 to 4.5 V, Pout _{DCS} ≤ 32.0 dBm, Vapc ≤ 2.2 V, Rg = 50 Ω, Output VSWR = 6 : 1 All phase angles
Load VSWR tolerance	—	No degradation or Permanent degradation			—	Vdd = 3.1 to 4.5 V, Pout _{DCS} ≤ 32.0 dBm, Vapc ≤ 2.2 V, Rg = 50 Ω, t ≤ 20 sec., Output VSWR = 10 : 1 All phase angles
Load VSWR tolerance at GPRS CLASS 12 operation	—	No degradation or Permanent degradation			—	Vdd = 3.1 to 4.2 V, Pout _{DCS} ≤ 32.0 dBm, Vapc ≤ 2.2 V, Rg = 50 Ω, t ≤ 20 sec., Tc ≤ 90°C, Output VSWR = 10 : 1 All phase angles
Slope Pout/Vapc	—	—	160	200	dB/V	Pout _{DCS} = 0 to 32.0 dBm
AM output	—	—	15	20	%	Pout _{DCS} = 0 to 32.0 dBm, 4% AM modulation at input 50 kHz modulation frequency

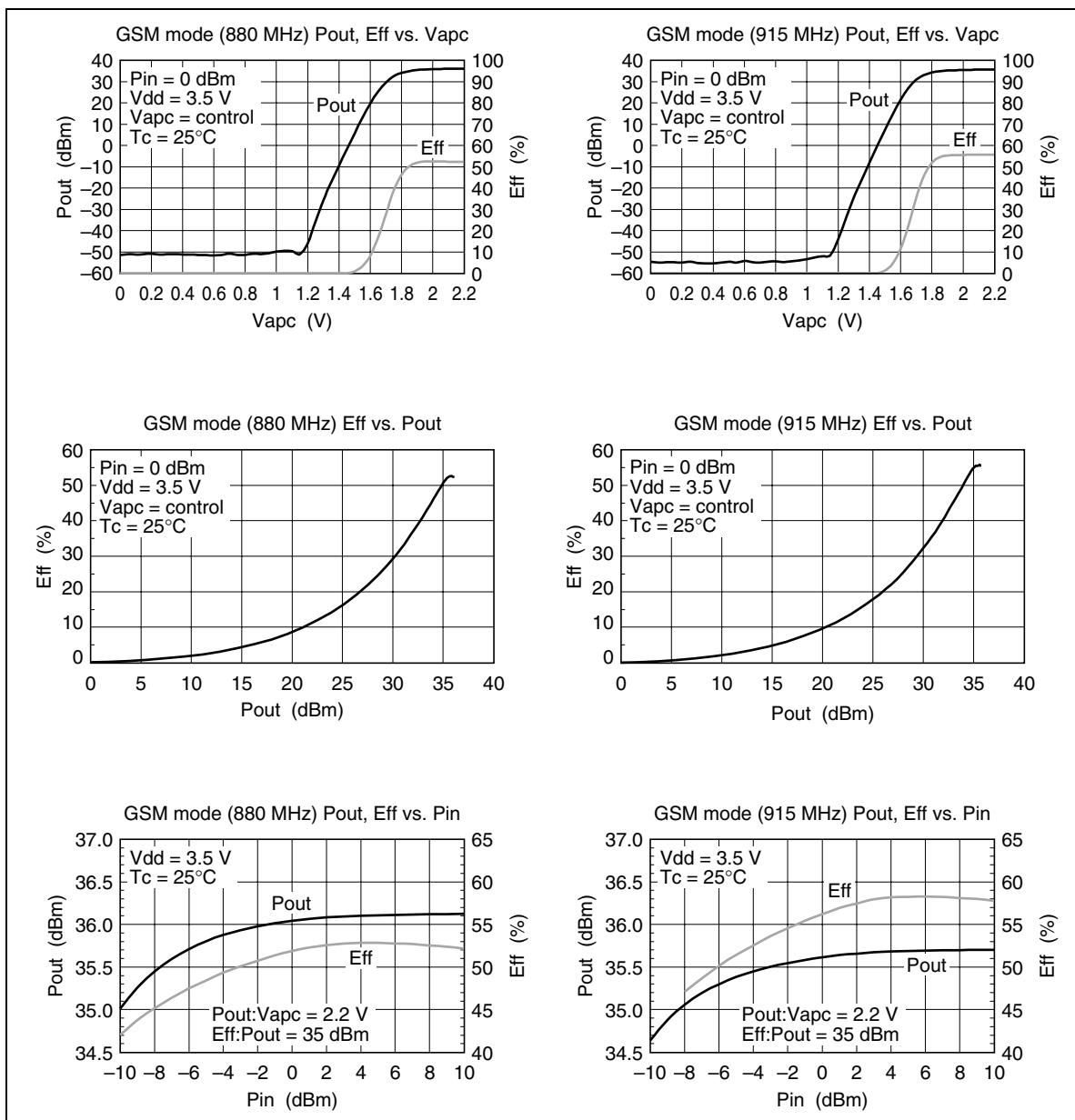
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Circuit Diagram

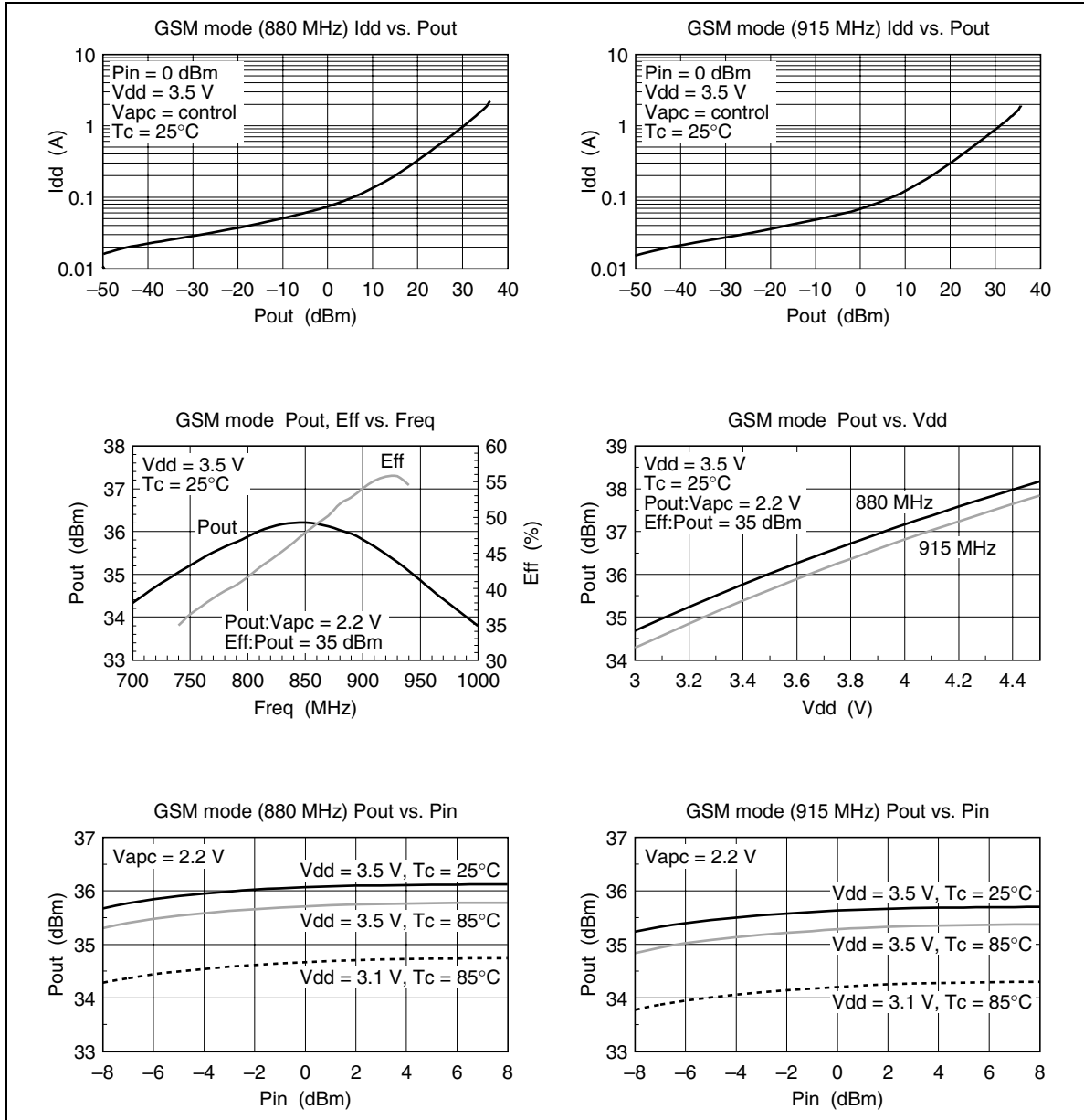


Characteristic Curves

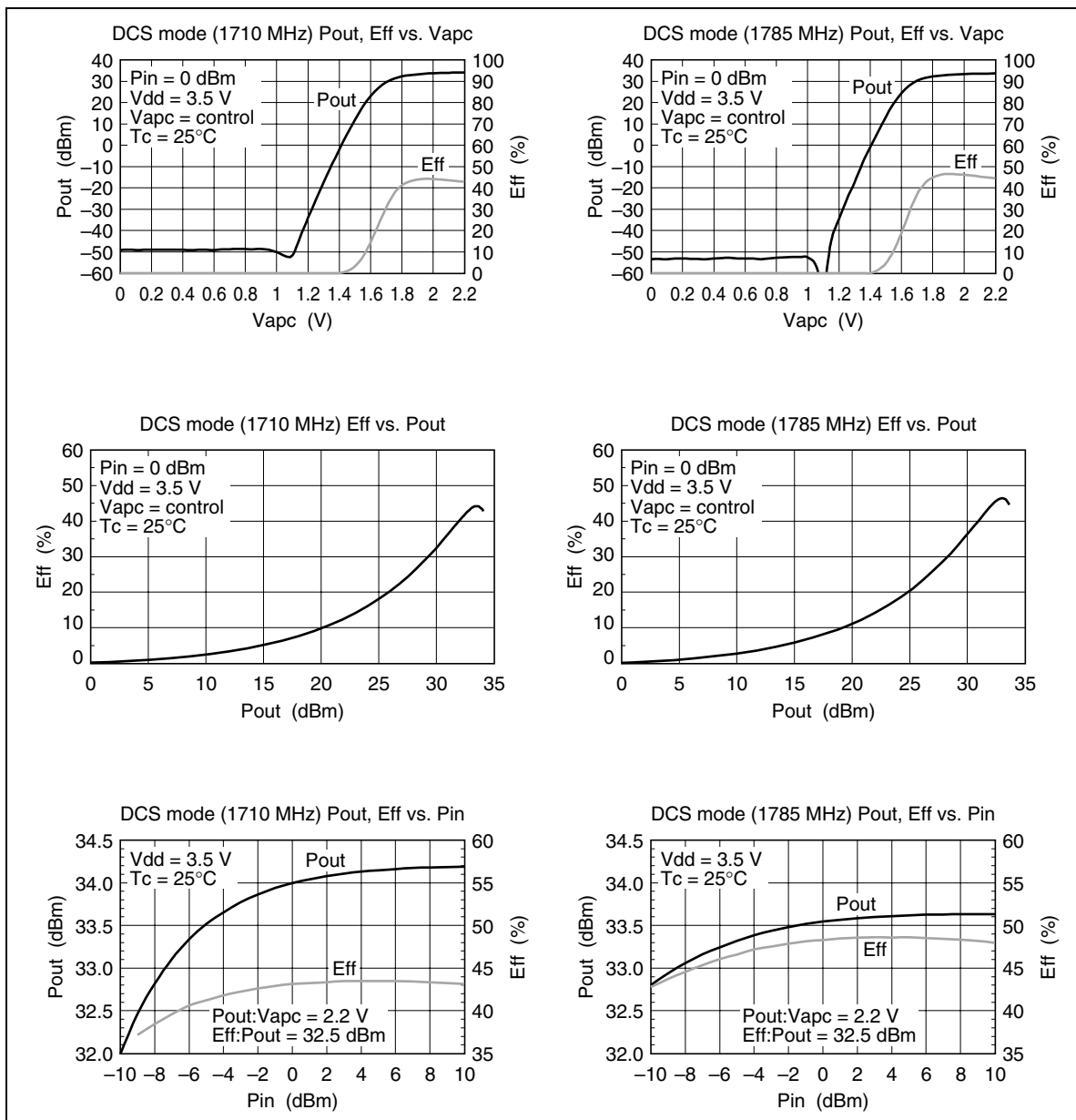
GSM mode (880MHz to 915 MHz)



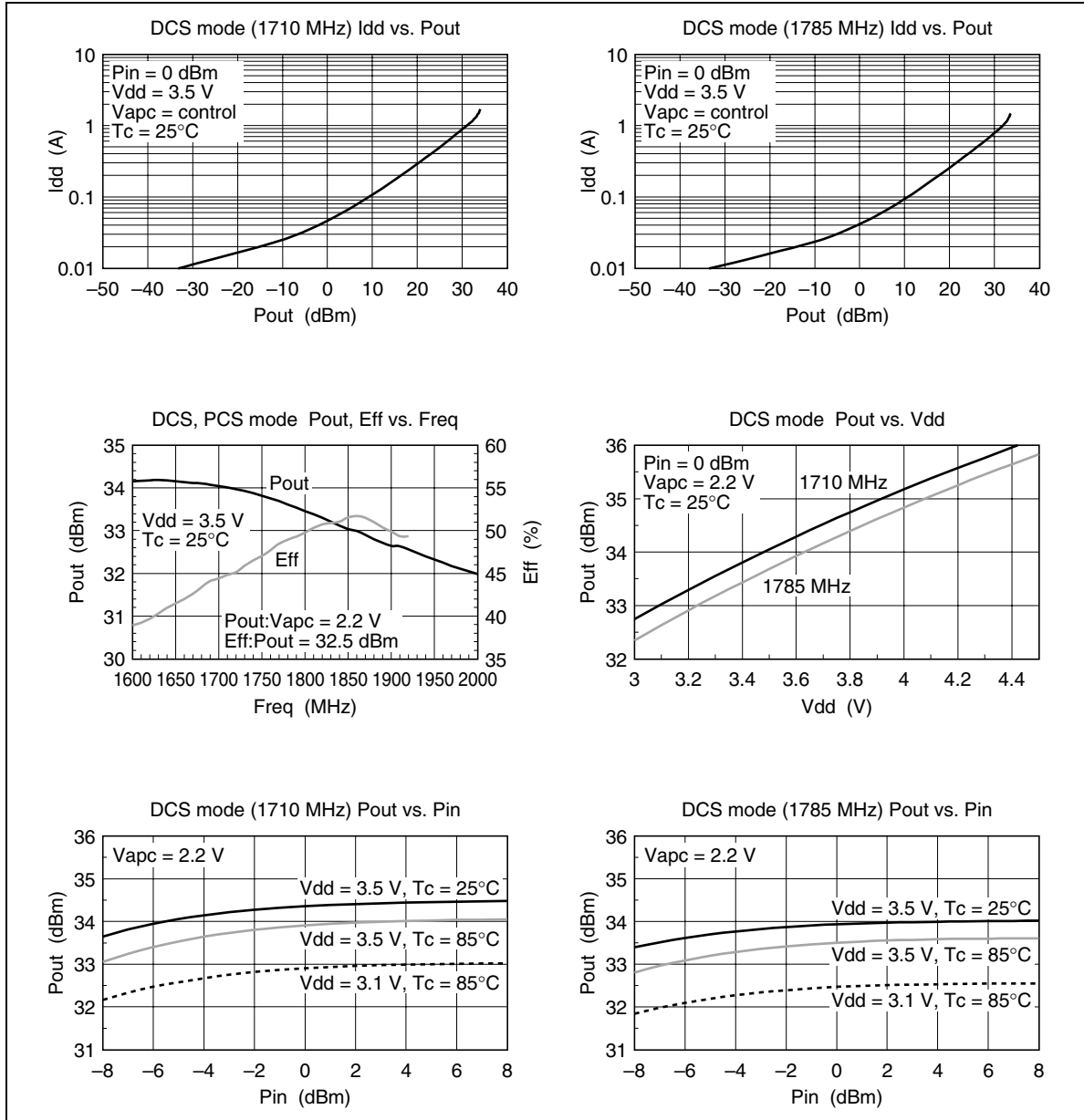
GSM mode (880MHz to 915 MHz) (cont.)



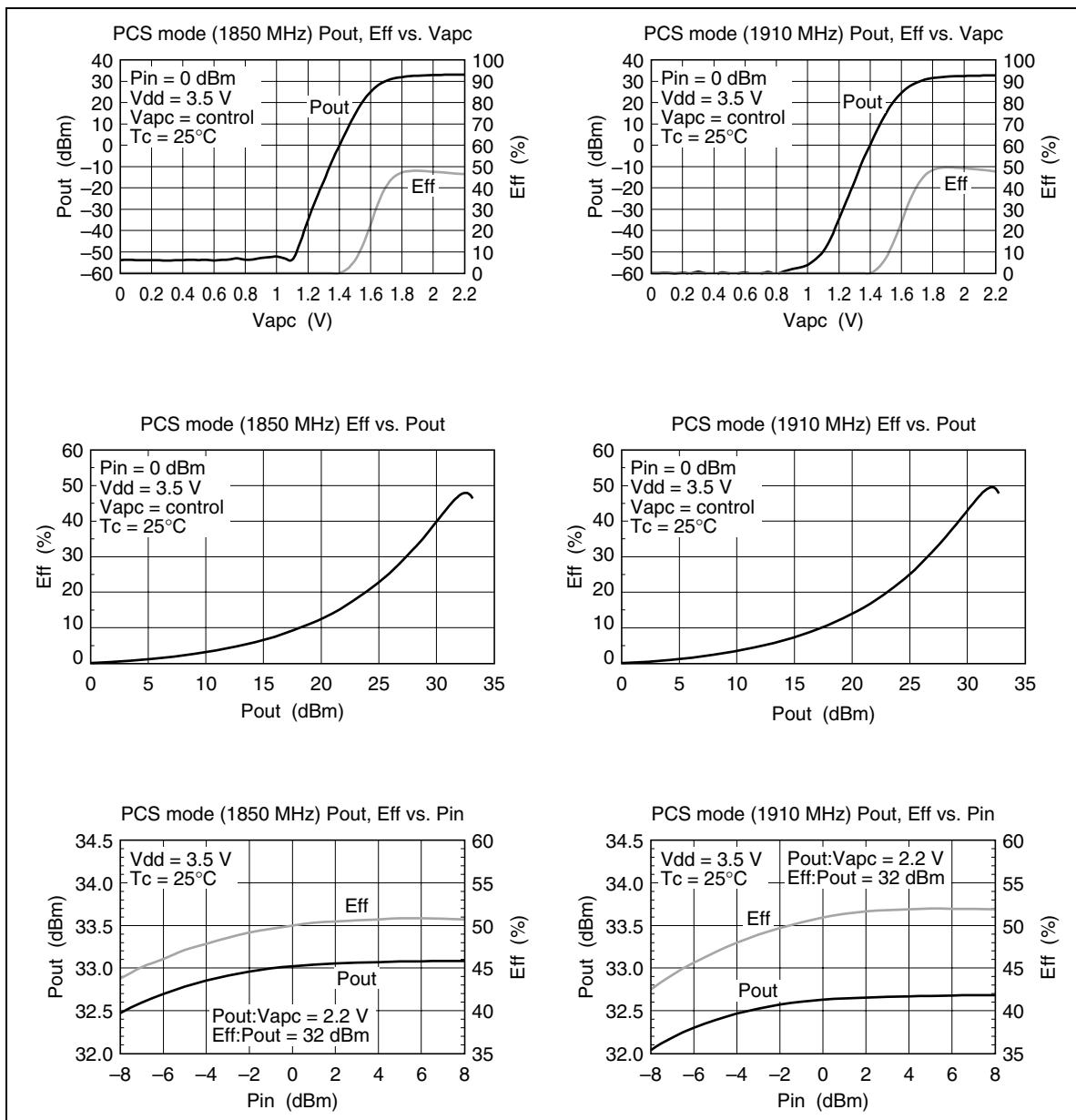
DCS mode (1710MHz to 1785 MHz)



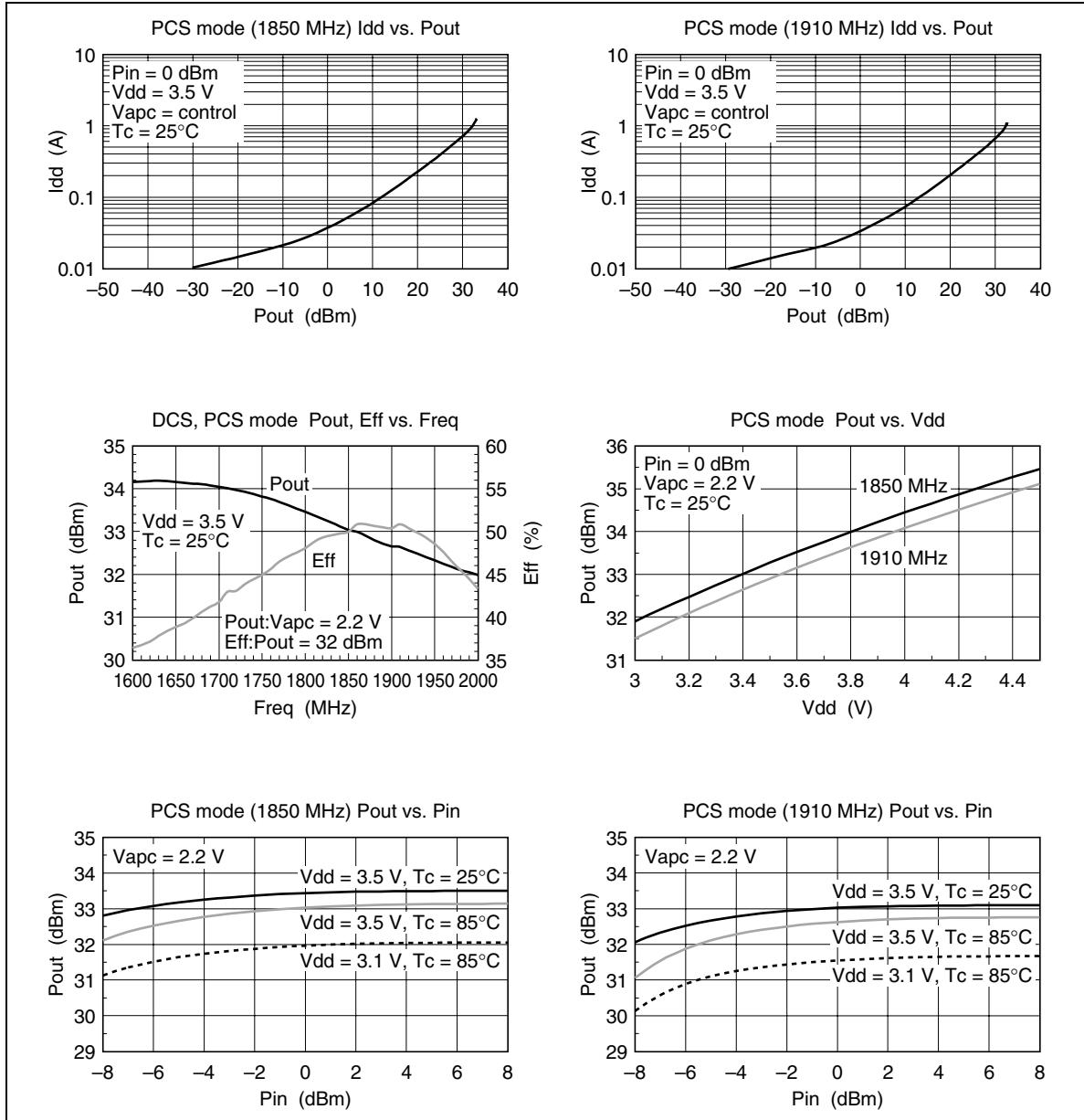
DCS mode (1710MHz to 1785 MHz) (cont.)



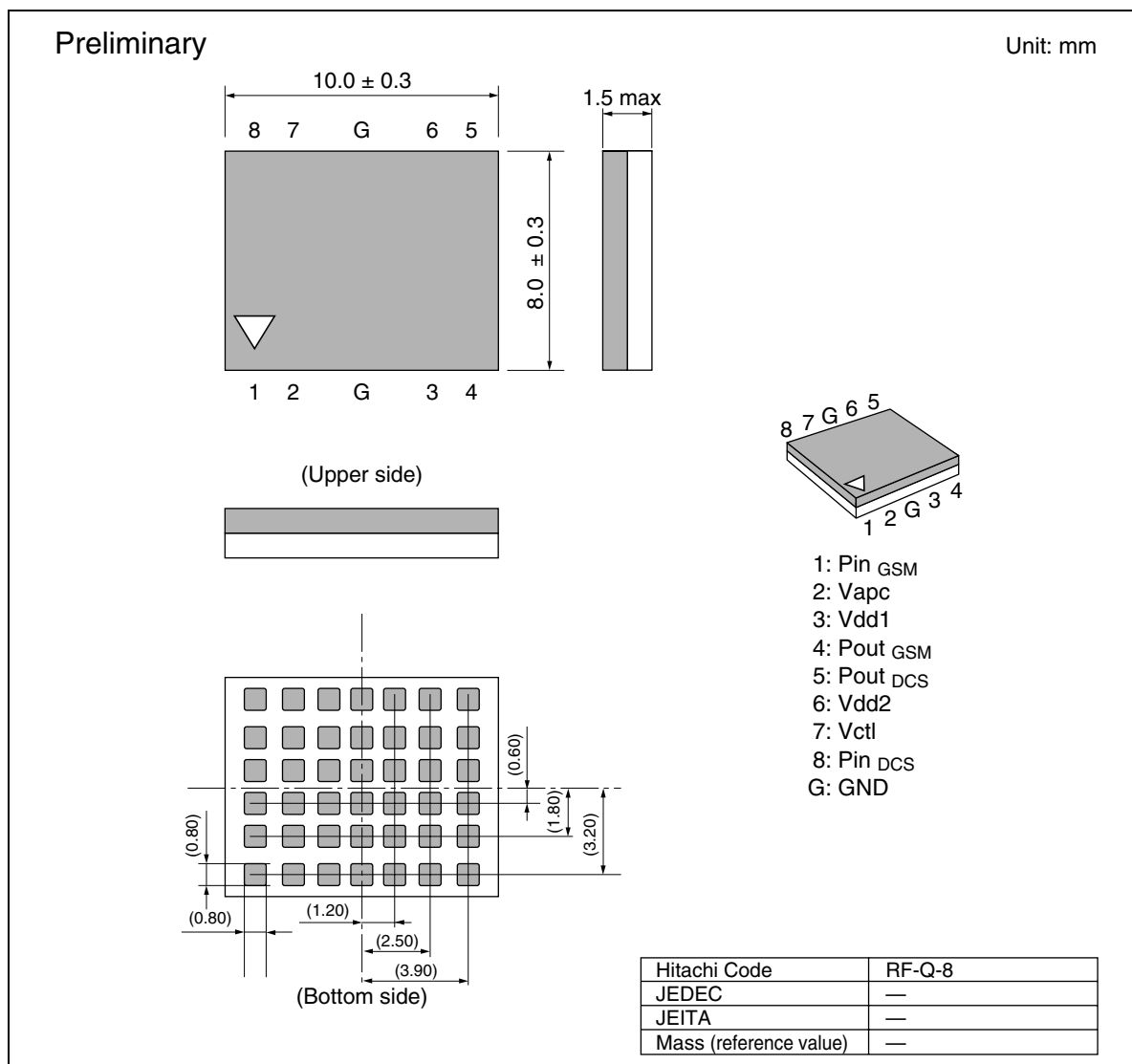
PCS mode (1850MHz to 1910 MHz)



PCS mode (1850MHz to 1910 MHz) (cont.)



Package Dimensions



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